| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|--|---|---------------------|-----------|------------------|
| L1 | 61 | 324/765.ccls. and (insulating near film) and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:22 |
| L2 | | 324/671.ccls. and (insulating near film) and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:22 |
| L3 | 0 | 324/455.ccls. and (insulating near film) and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:26 |
| L4 | 65 | 438/16.ccls. and (insulating near film) and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:23 |
| L5 | 90 | 438/17.ccls. and (insulating near film) and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:25 |
| L7 | 24 | 324/455.ccls. and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:26 |
| S1 | 0 | 702/57.ccls. and (insulating near film) and thickness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON . , | 2005/03/24 16:21 |
| S2 | 2 | 702/57.ccls. and (insulating near film) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:05 |

| S3 | 46609 | (insulating near film) and thickness and substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON . | 2005/03/18 16:06 |
|-----------|-------|---|---|----|------|------------------|
| S4 | 7967 | S3 and voltage and nitrogen | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:07 |
| S5 | 2733 | S4 and charge and deposition | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:07 |
| S6 | 2620 | S5 and oxide | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:08 |
| S7 | 687 | S6 and leak | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:08 |
| S8 . | 367 | S7 and uniform | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:11 |
| S9 | 309 | substrate and film and thickness and nitrogen and charge and deposition and (surface near voltage) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 16:27 |
| S10 | 46 | substrate and film and thickness and nitrogen and charge and deposition and (surface near voltage)and (non near contact) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON . | 2005/03/18 17:13 |

| S17 | 3731 | (measure or test) and (contactless or (non adj contact)) and oxide and film | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 17:15 |
|-----|-------|---|---|----|----|------------------|
| S18 | 80 | S17 and insulate and nitrogen | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/18 17:17 |
| S19 | 24422 | ((dielectric or insulating) with film) and substrate and thickness and nitrogen | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:11 |
| S20 | 5571 | ((dielectric and insulating) with film) and substrate and thickness and nitrogen | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:30 |
| S21 | 1195 | S20 and (surface with voltage) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:11 |
| S22 | 614 | S21 and charge and deposition | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:12 |
| S23 | 7 | S22 and leaky | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:13 |
| S24 | 577 | S22 and current | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:13 |

| | | | 110 505:15 | 00 | <u> </u> | 2005/02/22 11 15 |
|-----|-----|---|---|------|----------|------------------|
| S25 | 560 | S24 and oxide | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:15 |
| S26 | 62 | S20 and S21 and S22 and S24 and S25 and (contactless or non-contact) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:16 |
| S27 | 0 | ((dielectric and insulating) with film with measuring with thickness) and substrate and nitrogen | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:30 |
| S28 | 90 | ((dielectric or insulating) with film with measuring with thickness) and substrate and nitrogen | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/22 14:31 |
| S30 | 176 | substrate and (dielectric near film) and (electrical near measurement) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR · | ON | 2005/03/23 11:22 |
| S31 | 116 | substrate and (dielectric near film) and (electrical near measurement) and voltage | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:58 |
| S32 | 9 | substrate and (dielectric near film) and (electrical near measurement) and voltage and (kelvin or monroe with probe) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 14:11 |
| S33 | 0 | "6680621".uref. | USPAT; USOCR | OR | OFF | 2005/03/23 14:56 |
| S34 | 0 | "6597193".uref. | USPAT; USOCR | OR | OFF | 2005/03/23 14:33 |
| S35 | 93 | substrate and (dielectric near film) and voltage and (kelvin or monroe with probe) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 14:11 |

| S39 | 29 | contactless and characterization and (dielectric with film) and | USPAT; USOCR | OR | ON | 2005/03/23 17:51 |
|-----|----|---|-----------------|----|----|------------------|
| ; | | voltage and thickness | | | | |